ASSOCIATION CONNECTED ELECTRONICS INDUST	© Copyright 2005, IPC.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and M	als and Mfg Information			
Supplier Info	rmation														
Company name*			Company unique ID			U	Unique ID Authority					Response Date*			
nsemi											2024-05-	2024-05-12			
Contact Name		Title - Contact			P	Phone - Contact*				Email -	Email - Contact*				
Product-Env-Ste	ewards	Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com					
uthorized Repr	esentative*	Title - Representative			P	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			N	NA				Product-Env-Stewards@onsemi.com				
Reque	ester Item Number Mfr Iter		m Number Mfr Item Name				Effective Dat	e Version	N	Manufacturing Site		Weight*	* UOM	Unit Ty	
		NCP718ASN250T1G 300 mA Low TSOP5 2V5		300 mA Low Iq, TSOP5 2V5 AD	Wide Input Voltage	LDO -	2024-05-12 THB		НВ	12.52		mg	Each		
Ianufacturin	ng Proccess Information	n													
Termin	nal Plating / Grid Array Materi	Plating / Grid Array Material Terr		Γerminal Base Alloy J		J-STD-020 MSL Rating		Peak Process Body Temperatur		re Max Time at Peak Tempera		ature Number of Reflow Cycles			
Precio Sn)			CU Alloy 1		1		260		C 30		secon	seconds 3			
Comments															
vel 1 - maximur	n time at peak temperature	during sol	dering is 10-3	0 seconds											
or more inform	ation regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.3	mg	Supplier	Silicon (Si)	7440-21-3		0.3	mg
Die Attach Epoxy	0.1	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.085	mg
			Supplier	Proprietary	Proprietary Data		0.005	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.007	mg
Lead Frame	6.43	mg	Supplier	Zinc (Zn)	7440-66-6		0.0077	mg
			Supplier	Iron (Fe)	7439-89-6		0.1511	mg
			Supplier	Copper (Cu)	7440-50-8		6.2692	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0019	mg
Mold Compound-Black	5.6	mg		Epoxy resin	proprietary data		0.28	mg
			Supplier	Phenolic Resin	Proprietary Data		0.112	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.14	mg
			Supplier	Carbon Black (C)	1333-86-4		0.028	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.04	mg
Plating	0.07	mg	Supplier	Palladium (Pd)	7440-05-3		0.0017	mg
			В	Nickel (Ni)	7440-02-0		0.0616	mg
			Supplier	Gold (Au)	7440-57-5		0.0067	mg
Wire Bond - Cu	0.02	mg	Supplier	Palladium (Pd)	7440-05-3		0.0004	mg
			Supplier	Gold (Au)	7440-57-5		0	mg
			Supplier	Copper (Cu)	7440-50-8		0.0196	mg